## Ishii Hyoki and Tera Probe Develop World First Inkjet Coater for WLP and Bumping

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Ishii Hyoki Co., Ltd. and Tera Probe, Inc. today announced that they have jointly developed the semiconductor industry's first inkjet coater for wafer level package (WLP) and bumping process coating using an inkjet method to apply thick-film insulating coating (polyimides).

The usual method for insulating film coating during the WLP and bumping manufacturing processes uses a spin coater to apply the coating. In contrast, the inkjet coater jointly developed by Ishii Hyoki and Tera Probe directly sprays micronized insulating material onto the target wafer. The same insulating material can easily be switched to thick-film coating. Also, the new inkjet coater offers a higher level of productivity by eliminating the kind of cleaning process needed for conventional spin coaters.

## Key features of the inkjet coater:

- 1. Can use the same polyimide materials used by conventional spin coaters to achieve high quality, highly efficient coating.
- 2. Can flexibly adjust film thickness for 200-300mm wafers.
- 3. Redistribution layer with major irregularities can be easily coated to achieve superior uniformity.

Tera Probe will take advantage of these inkjet coater features in the development of existing and future products. The company will continue to provide its customers and the market with customized WLP and bumping services.

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